



注記 NOTES:

1. 使用材料 MATERIAL
 ウェハー: 液晶ポリマー ガラス充填 ,UL94V-0(黒)
 WAFER :LIQUID CRYSTAL POLYMER
 (GLASS FILLED), UL94V-0 (COLOR:BLACK)
 ピン :黄銅 (t=0.15)
 PIN :BRASS(t=0.15)
2. メッキ仕様 PLATING
 金メッキ 0.25 MICROMETER MINIMUM (コンタクト部)
 GOLD 0.25 MICROMETER MINIMUM (CONTACT AREA).
 金メッキ 0.4 MICROMETER MAXIMUM (テール部)
 GOLD 0.4 MICROMETER MAXIMUM (TAIL AREA).
 下地メッキ: ニッケルメッキ 1.5 MICROMETER MINIMUM
 UNDER PLATING : NICKEL 1.5 MICROMETER MINIMUM.
3. (全極数/2) = 偶数の場合に適用。
 APPLY FOR (CIRCUIT/2)=EVEN.
4. 嵌合相手: 54722 シリーズ, 54037 シリーズ
 MATE WITH : 54722 SERIES, 54037 SERIES.
5. テール平坦度は、0.1 MAXIMUM
 TAIL COPLANARITY TO BE 0.1 MAXIMUM.

嵌合断面図 (参考)
MATED DRAWING (REF.)

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| REVISED EC NO: J2012-0135 DRWN: YON002 2011/07/01 CHKD: TASAKAWA 2011/07/01 APPR: MSASAO 2011/07/29 K | DESCRIPTION REV | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE --- | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | | |
| | | 10 UNDER | ± 0.20 | DRAWN BY SAIHARA | DATE 2000/10/05 | TITLE 0.5 B-T-O-B CONN PLUG ASSY (HGT=1.5) | | | | |
| | | 10 OVER 30 UNDER | ± 0.25 | CHECKED BY MSASAO | DATE 2003/03/31 | APPROVED BY MSASAO 2003/03/31 | | | | |
| | | 30 OVER | ± 0.30 | ANGULAR ±3 ° | | MATERIAL NO. SEE SHEET 1 | | DOCUMENT NO. SD-55560-006 | | SHEET NO. 2 OF 2 |
| | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | |